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Reliability, Packaging, Testing, and Characterization of MEMS/MOEMS VI

Allyson L. Hartzell
Rajeshuni Ramesham
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Contents

vii	Conference Committee
ix	Introduction

SENSORS: APPLICATIONS AND RELIABILITY METHODOLOGY

- 646302 **Receptor-free nanomechanical sensors (Keynote Paper)** [6463-01]
L. R. Senesac, D. Yi, T. Thundat, Oak Ridge National Lab. (USA)
- 646303 **New techniques for detecting and monitoring corrosion using nanostructures (Invited Paper)** [6463-02]
C. O. Muller, W. G. England, Purafil, Inc. (USA)
- 646304 **Hybrid approach to MEMS reliability assessment** [6463-03]
J. L. Zunino III, D. R. Skelton, U.S. Army RDE Command (USA); W. Han, R. J. Pryputniewicz, WPI-ME (USA)

RF MEMS AND RELATED FAILURE MECHANISMS

- 646305 **Metal contact reliability of RF MEMS switches (Invited Paper)** [6463-04]
Q. Ma, Q. Tran, T.-K. A. Chou, J. Heck, H. Bar, R. Kant, V. Rao, Intel Corp. (USA)
- 646306 **Effects of V additions on the mechanical behavior of Au thin films for MEMS contact switches** [6463-05]
T. Bannuru, Lehigh Univ. (USA); S. Narksitipan, Chiang Mai Univ. (Thailand); W. L. Brown, R. P. Vinci, Lehigh Univ. (USA)
- 646307 **Mechanics of thin film adhesion-delamination subjected to residual stress and interfacial adhesion: application to MEMS-RF-switch** [6463-06]
M. F. Wong, K.-T. Wan, Univ. of Missouri-Rolla (USA)

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MEMS MATERIALS PROPERTIES

- 646309 **A novel technique for extraction of material properties through measurement of pull-in voltage and off-capacitance of beams** [6463-09]
J. Sharma, A. DasGupta, Indian Institute of Technology, Madras (India)
- 64630A **Cyclic thin film flexible pressure sensor testing** [6463-10]
H. C. Lim, New Jersey Institute of Technology (USA); J. L. Zunino III, U.S. Army ARDEC (USA); J. F. Federici, New Jersey Institute of Technology (USA)
- 64630B **Self-sensing and actuation of CNF and Ni nanowire/polymer composites using electromicromechanical test** [6463-11]
J.-M. Park, Gyeongsang National Univ. (South Korea) and Univ. of Utah (USA); S.-J. Kim, P.-G. Kim, Gyeongsang National Univ. (South Korea); D.-J. Yoon, Korea Research Institute of Standard and Science (South Korea); G. Hansen, Metal Matrix Composites Inc. (USA); K. L. DeVries, Univ. of Utah (USA)
- 64630C **Critical comparison of metrology techniques for MEMS** [6463-12]
M. G. da Silva, Exponent Inc. (USA); S. Bouwstra, MEMS TC (Netherlands)

MEMS RELIABILITY

- 64630D **MEMS reliability assessment program: progress to date (Invited Paper)** [6463-13]
J. L. Zunino III, D. R. Skelton, U.S. Army RDE Command (USA)
- 64630E **Development of a model for predicting dry stiction in microelectromechanical systems (MEMS)** [6463-14]
A. Hariri, J. W. Zu, R. Ben Mrad, Univ. of Toronto (Canada)

OPTICAL MEMS: DESIGN FOR RELIABILITY AND CHARACTERIZATION TECHNIQUES

- 64630F **Optical MEMS: designing for reliability (Invited Paper)** [6463-15]
S. Bhattacharya, Indian Institute of Technology, Madras (India)
- 64630G **Process engineering and failure analysis of MEMS and MOEMS by digital holography microscopy (DHM)** [6463-16]
F. Montfort, Y. Emery, F. Marquet, E. Cuhe, N. Aspert, E. Solanas, Lyncée Tec SA (Switzerland); A. Mehdaoui, A. Ionescu, C. Depeursinge, EPFL (Switzerland)
- 64630H **Performance and reliability test of MEMS optical scanners** [6463-17]
S. Kurth, Fraunhofer Institute for Reliability and Microintegration (Germany); C. Kaufmann, R. Hahn, Chemnitz Univ. of Technology (Germany); J. Mehner, Fraunhofer Institute for Reliability and Microintegration (Germany); W. Dötzel, Chemnitz Univ. of Technology (Germany); T. Gessner, Fraunhofer Institute for Reliability and Microintegration (Germany) and Chemnitz Univ. of Technology (Germany)
- 64630I **White light interferometric profile measurement system using spectral coherence** [6463-18]
G.-W. Chang, Y.-H. Lin, Z.-M. Yeh, National Taiwan Normal Univ. (Taiwan)

SPECIAL TOPICS IN MEMS I

- 64630J **Charging effects in spatial light modulators based on micromirrors** [6463-20]
U. Dauderstädt, T. Bakke, P. Dürr, S. Sinning, I. Wullinger, M. Wagner, H. Lakner, Fraunhofer
Institute for Photonic Microsystems (Germany)
- 64630K **On the reliability of thermopneumatic actuators with silicon membranes** [6463-21]
A. K. Henning, Aquarian Microsystems (USA)
- 64630L **Testing reliability of MEMS materials in liquids** [6463-22]
T. P. Kuehn, S. M. Ali, S. C. Mantell, E. K. Longmire, Univ. of Minnesota (USA)

SPECIAL TOPICS IN MEMS II

- 64630M **Wafer capping of MEMS with fab-friendly metals (Invited Paper)** [6463-23]
J. Martin, Analog Devices, Inc. (USA)
- 64630N **Simple measurement technique for resonance frequency of micromachined cantilevers**
[6463-24]
S. Bhat, E. Bhattacharya, Indian Institute of Technology Madras (India)
- 64630O **Analytical model of a single stage compliant mechanism with flexible lever beam**
[6463-25]
P. A. Hassanpour, W. L. Cleghorn, Univ. of Toronto (Canada); E. Esmailzadeh, Univ. of
Ontario Institute of Technology (Canada); J. K. Mills, Univ. of Toronto (Canada)
- 64630P **A fast model-order reduction algorithm for microelectromechanical devices** [6463-26]
R. Zhang, P. Zhang, G. A. Jullien, Univ. of Calgary (Canada)
- 64630Q **Development of wireless MEMS sensor for RFID tag and temperature/pressure monitoring**
[6463-27]
W. Wang, K. Lee, T. Kim, S. Yang, Ajou Univ. (South Korea)

Author Index

Conference Committee

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Sensors: Applications and Reliability Methodology

Enakshi Bhattacharya, Indian Institute of Technology Madras (India)

RF MEMS and Related Failure Mechanisms

Olivier N. Pierron II, Qualcomm MEMS Technologies (USA)

MEMS Materials Properties

Christopher K. Harrison, Schlumberger Ltd. (USA)

MEMS Reliability

Jason O. Clevenger, Exponent Inc. (USA)

Optical MEMS: Design for Reliability and Characterization Techniques

Danelle M. Tanner, Sandia National Laboratories (USA)

Special Topics in MEMS I

Peter Basque, Analog Devices, Inc. (USA)

Special Topics in MEMS II

Herbert R. Shea, Swiss Federal Institutes of Technology (Switzerland)

Introduction

The reliability, packaging, testing, and characterization of MEMS/MOEMS are of significant importance to the commercialization of these advanced and useful technologies. The objective of this conference is to provide a technical forum for in depth investigations and interdisciplinary discussions. The response to the call for papers has been overwhelming and rewarding.

The Reliability, Packaging, Testing, and Characterization of MEMS/MOEMS Conference is sponsored by SPIE and organized as part of Photonics West 2007, it is part of the MOEMS-MEMS 2007 Micro-Nano Fabrication Symposium, and an education program on MOEMS-MEMS held January 20–25, 2007 in San Jose Convention Center, San Jose, California, USA. SPIE is the premier international forum for presentation of the latest developments associated with MEMS and MOEMS including reliability, testing, packaging, materials, surfaces, and characterization. This conference has been held for several years in row.

In preparing for the conference, 24 high-quality papers were received from researchers in various countries and universities. Nine sessions cover MOEMS-MEMS plenary presentations, applications and reliability methodology, RF MEMS and related failure mechanisms, MEMS materials properties, MEMS reliability, optical MEMS design for reliability and characterization techniques, MEMS/MOEMS reliability methodology, MEMS/MOEMS characterization techniques, and special topics in MEMS. We have put together a technical program with seven invited speakers, three plenary speakers from reputed laboratories around the country/globe, and a keynote speaker from Oak Ridge National Laboratory whose presentation is "Receptor free nanomechanical sensing".

We also arranged a panel discussion on "MEMS reliability" for the first time. The panel will be moderated by Jason Clevenger, Exponent Inc. Panel members Peter Basque, Analog Devices; Bill Cummings, Qualcomm; Charles King, Akustica; Danelle Tanner, Sandia National Labs., and Jim Aberson, Colibrys, are highly recognized in this research field.

We would like to personally thank Dr. Danelle Tanner (past reliability conference chair) of Sandia National Labs. and Dr. Al Henning (symposium co-chair) for their unstinting timely support and encouragement. Finally, we would like to thank all the session chairs, co-chairs, and program committee members for their support in organizing this conference so successfully.

**Allyson L. Hartzell
Rajeshuni Ramesham**